## Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

## **Listing of Claims:**

Claim 1 (currently amended). A pressure stamp device for sealing of films with a heatable stamping element having a stamping surface for applying a pressure to a first film in order to bond it with a supported second film, characterized in that the stamping element has a multilayer configuration and comprises basically three layers including a heated central layer of a first material with a high thermal conductivity value flanked by two peripheral layers of a second material steel, one of which forms the stamping surface.

Claim 2 (original). The device according to claim 1 characterized in that the two peripheral layers are of identical thickness.

Claim 3 (previously presented). The device according claim 1 characterized in that the central layer is made of copper.

Claim 4 (previously presented). The device according to claim 1 characterized in that the central layer is made of aluminum.

Claim 5 (previously presented). The device according to claim 1 characterized in that the central layer has a thickness of about 20 mm.

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Claim 6 (canceled).

Claim 7 (currently amended) The device according to claim 6 1 characterized in that the steel layers have a thickness of about 10 mm to 15 mm.

Claim 8 (previously presented). The device according claim 1 characterized in that bores are provided in the central layer through which heating elements are passed.

Claim 9 (currently amended). The device according to claim 8 characterized in that the heating elements are electrically heatable heating the wires.

Claim 10 (previously presented) The device according to claim 1 wherein the stamping element is rectangular.

Claim 11 (previously presented). The device according to claim 1 characterized in that the stamping element is circular.

Claim 12 (currently amended) The device according to claim 1 characterized in that A pressure stamp device for sealing of films with a heatable stamping element having a stamping surface for applying a pressure to a first film in order to bond it with a supported second film, characterized in that the stamping element has a multilayer configuration and comprises three layers including a heated central layer of a first material with a high thermal conductivity value flanked by two peripheral layers of a second material, one of which forms the stamping surface, and wherein in a central region the stamping element is traversed by a hollow cylindrical bore

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through all layers in which a cylindrical pin is fitted.

Claim 13 (currently amended). The device according to claim 1 characterized in that A pressure stamp device for sealing of films with a heatable stamping element having a stamping surface for applying a pressure to a first film in order to bond it with a supported second film, characterized in that the stamping element has a multilayer configuration and comprises three layers including a heated central layer of a first material with a high thermal conductivity value flanked by two peripheral layers of a second material, one of which forms the stamping surface, and wherein in an off-center region the peripheral layers of the stamping element have a slot and in the region of the slot in the central layer a bore is provided in which a further pin is fitted which is slidable in the slot.

Claim 14 (currently amended). The device according to claim 1 characterized in that A pressure stamp device for sealing of films with a heatable stamping element having a stamping surface for applying a pressure to a first film in order to bond it with a supported second film, characterized in that the stamping element has a multilayer configuration and comprises three layers including a heated central layer of a first material with a high thermal conductivity value flanked by two peripheral layers of a second material, one of which forms the stamping surface, and wherein the peripheral layers are secured together by screws traversing the central layer.

Claim 15 (previously presented). The device according to claim 1 characterized in that the stamping element is square with an edge length of about 300 mm.